

File E123948

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and Report

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ENGINEERING CONSIDERATIONS (NOT FOR FIELD REPRESENTATIVE'S USE):

Use - For use only in complete equipment where the acceptability of the combination is determined by Underwriters Laboratories Inc.

Conditions of Acceptability -

1. Polymeric enclosure devices has been investigated for suitability as part of a Type 1 enclosure. The supply leads must be suitably enclosed.
2. This device should be used within its marked electrical rating.
3. This device was tested within an unventilated enclosure of 6 x 5 x 9-1/2 in. If mounted within a smaller enclosure, consideration should be given for the need of repeating temperature tests.
4. The temperature of the device of polymeric enclosure shall not exceed 130°C in the end-use application in normal modes operation with the HID lamp energized.
5. The temperature of the device of polymeric enclosure shall not exceed 130°C in the end-use application in the abnormal mode of operation of the incandescent lamp continuously energized.
6. The temperature of the device of Aluminum enclosure shall not exceed 105°C.
7. The devices have not been evaluated for exposure to weather.
8. The device was tested and found to be acceptable for use in a 25°C ambient. Acceptable operation at higher temperature shall be determined in the end used application.
9. Suitability of mounting shall be determined in the end use application.
10. The lead wire length shall comply with the requirements of the final application.
11. The devices shall be within an electrical enclosure having adequate strength and thickness as determined in the end-use application.
12. The Mold Stress Relief Test was conducted at a temperature of 115°C. Consideration shall be given to reconducting this test when the enclosure temperature exceeds 105°C in the end product.